



Biomaterials and Bioimaging: From Biological Tissues to Biomedical Implants

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Message from the Guest Editors

Biomedical engineering is a multidisciplinary field that applies principles of chemistry, physics, material science, and mechanical engineering into biology to find and treat diseases. Among various biomedical engineering areas, in particular, significant progress has been made in biomaterial and bioimaging research over the past few decades. Therefore, in-depth research on biomaterials and bioimaging will have a synergistic effect on understanding human diseases and can facilitate technological advances in preventing, monitoring, and treating diseases.

This Special Issue will include the latest innovations and emerging developments in biomaterials, bioimaging, and integrative research of these two areas. We have the great pleasure of inviting you to contribute research article(s) to this Special Issue.

Keywords

biomaterials
3D printing
metal implants
bioscaffolds
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tissue engineering
bioimaging
tissue optics
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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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